

## The RF Line

### NPN SILICON RF POWER TRANSISTOR

... designed for operation in driver and predriver stages for high power linear amplifiers, 2.0 to 30 MHz.

- Optimized for Operation from a 12.5 Volt Supply
- Power Gain @ 2.5 W (PEP) = 17 dB (Min)
- Intermodulation Distortion at Rated Power Output  
IMD = -35 dB (Max)

2.5 W (PEP)-30 MHz

RF POWER  
TRANSISTOR  
NPN SILICON

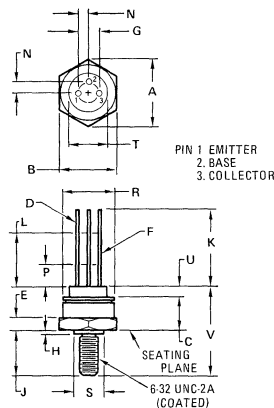


### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
* Collector-Emitter Voltage	$V_{CEO}$	18	Vdc
* Collector-Base Voltage	$V_{CBO}$	36	Vdc
* Emitter-Base Voltage	$V_{EBO}$	4.0	Vdc
* Collector Current – Continuous	$I_C$	1.0	Adc
* Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	10 57.2	Watts mW/ $^\circ\text{C}$
* Storage Temperature Range	$T_{stg}$	-65 to +200	$^\circ\text{C}$
Maximum Stud Torque (1)	—	2.1	in.-lb.

\* Indicates JEDEC Registered Data.

(1) For repeated assembly use 1.8 in.-lb maximum.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.49	11.00	0.413	0.433
B	9.19	9.53	0.362	0.375
C	5.33	5.72	0.210	0.225
D	0.406	0.533	0.016	0.021
E	1.65	1.78	0.065	0.070
F	0.406	0.483	0.016	0.019
G	2.54 BSC		0.100 BSC	
H	0.508	0.889	0.020	0.035
J	6.73	7.42	0.265	0.292
K	12.70	—	0.500	—
L	6.35	—	0.250	—
N	1.27 BSC		0.050 BSC	
P	—	1.27	—	0.050
R	8.89	9.14	0.350	0.360
S	4.45	4.83	0.175	0.190
T	4.11	4.29	0.162	0.169
U	1.14	1.52	0.045	0.060

CASE 24  
TO-102

\*ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $I_B = 0$ )	$BV_{CEO}$	18	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mAdc}$ , $V_{BE} = 0$ )	$BV_{CES}$	36	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 0.25 \text{ mAdc}$ , $I_C = 0$ )	$BV_{EBO}$	4.0	—	Vdc
Collector Cutoff Current ( $V_{CE} = 15 \text{ Vdc}$ , $V_{BE} = 0$ , $T_A = 125^\circ\text{C}$ )	$I_{CES}$	—	5.0	mAdc
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $I_C = 250 \text{ mAdc}$ , $V_{CE} = 5.0 \text{ Vdc}$ )	$h_{FE}$	5.0	50	—
<b>DYNAMIC CHARACTERISTICS</b>				
Current-Gain – Bandwidth Product ( $I_C = 150 \text{ mAdc}$ , $V_{CE} = 12.5 \text{ Vdc}$ , $f = 50 \text{ MHz}$ )	$f_T$	50	—	MHz
Output Capacitance ( $V_{CB} = 12.5 \text{ Vdc}$ , $I_E = 0$ , $f = 1.0 \text{ MHz}$ )	$C_{ob}$	—	20	pF
<b>FUNCTIONAL TESTS (Figure 1)</b>				
Common-Emitter Amplifier Power Gain ( $V_{CC} = 12.5 \text{ Vdc}$ , $P_{out} = 2.5 \text{ W (PEP)}$ , $f_1 = 30 \text{ MHz}$ , $f_2 = 30,001 \text{ MHz}$ )	$G_{PE}$	17	—	dB
Collector Efficiency ( $V_{CC} = 12.5 \text{ Vdc}$ , $P_{out} = 2.5 \text{ W (PEP)}$ , $f_1 = 30 \text{ MHz}$ , $f_2 = 30,001 \text{ MHz}$ )	$\eta$	38.5	—	%
Intermodulation Distortion ( $V_{CC} = 12.5 \text{ Vdc}$ , $P_{out} = 2.5 \text{ W (PEP)}$ , $f_1 = 30 \text{ MHz}$ , $f_2 = 30,001 \text{ MHz}$ )	IMD	—	-35	dB

\*Indicates JEDEC Registered Data

FIGURE 1 – 30 MHz TEST CIRCUIT

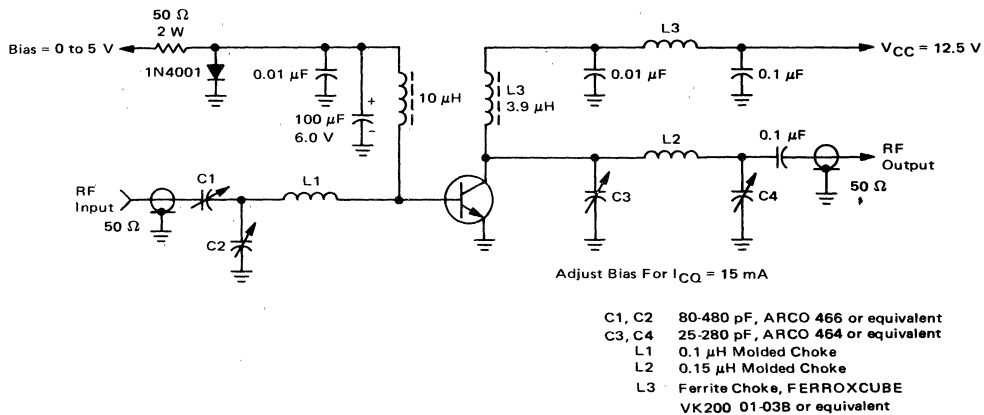


FIGURE 2 – LINEAR OUTPUT POWER versus FREQUENCY

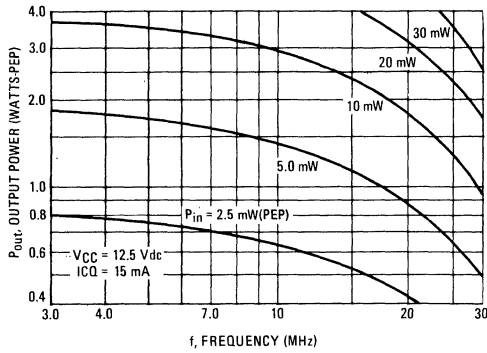


FIGURE 3 – OUTPUT POWER versus INPUT POWER (30 MHz)

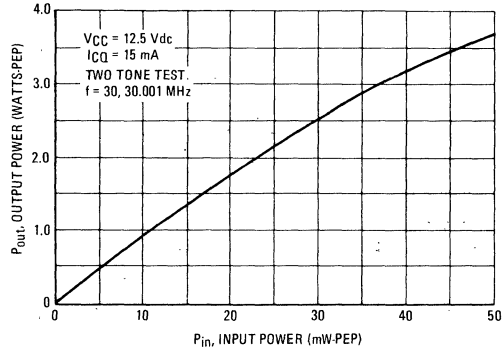


FIGURE 4 – OUTPUT POWER versus INPUT POWER (12 MHz)

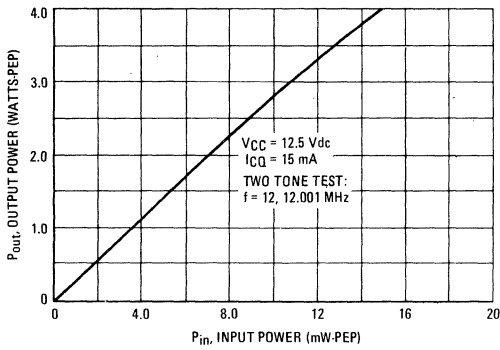


FIGURE 5 – OUTPUT POWER versus INPUT POWER (3.0 MHz)

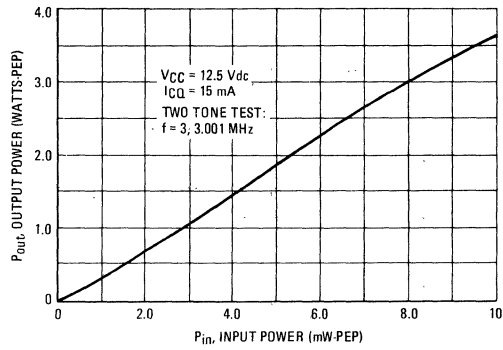


FIGURE 6 – INTERMODULATION DISTORTION versus OUTPUT POWER

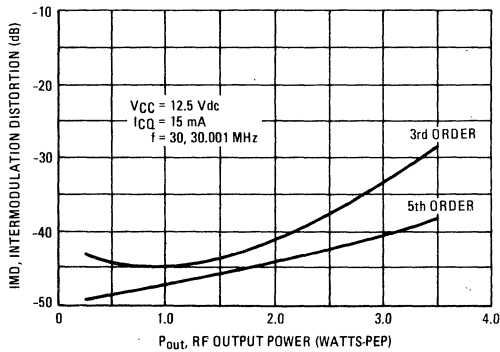


FIGURE 7 – LINEAR OUTPUT POWER versus SUPPLY VOLTAGE

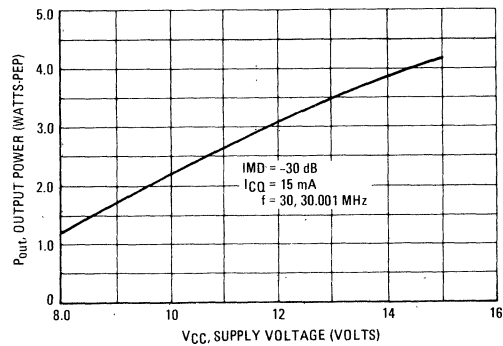


FIGURE 8 – PARALLEL EQUIVALENT INPUT RESISTANCE

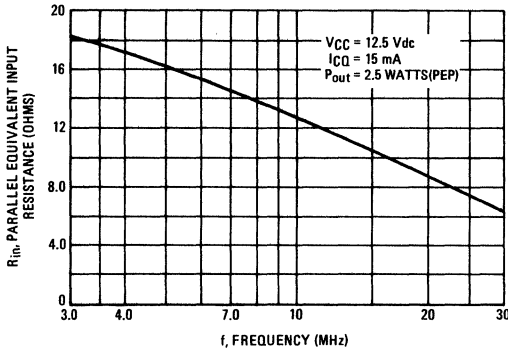


FIGURE 9 – PARALLEL EQUIVALENT INPUT CAPACITANCE

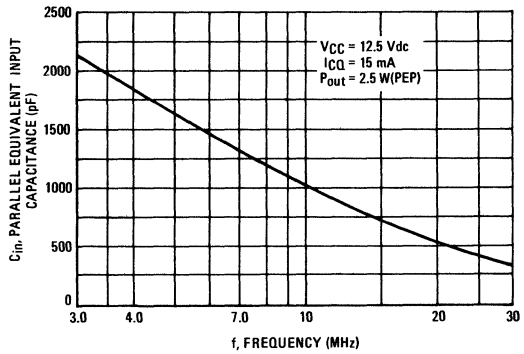


FIGURE 10 – PARALLEL EQUIVALENT OUTPUT RESISTANCE

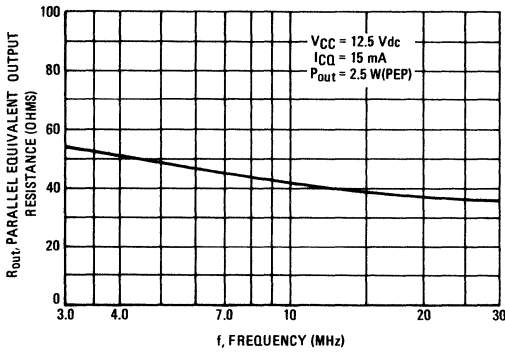


FIGURE 11 – PARALLEL EQUIVALENT OUTPUT CAPACITANCE

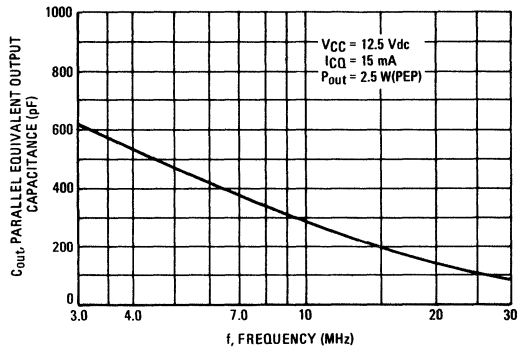


FIGURE 12 – CURRENT-GAIN – BANDWIDTH PRODUCT

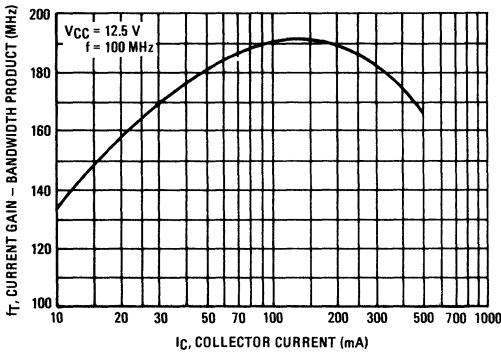


FIGURE 13 – COLLECTOR CURRENT versus BASE-EMITTER VOLTAGE

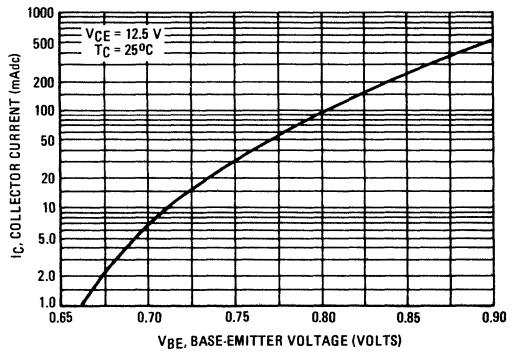


FIGURE 14 – OUTPUT CAPACITANCE versus VOLTAGE

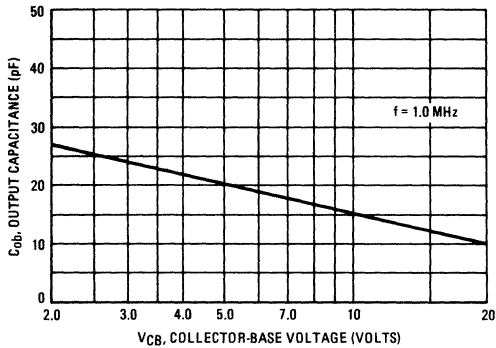


FIGURE 15 – INPUT CAPACITANCE versus VOLTAGE

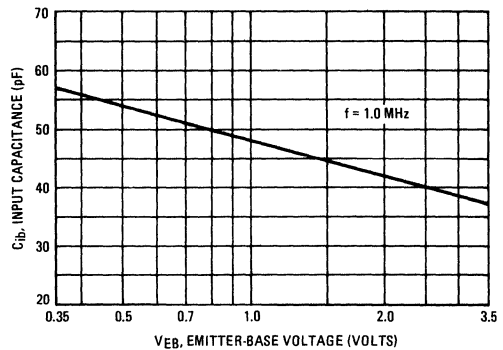


FIGURE 16 – DC SAFE OPERATING AREA

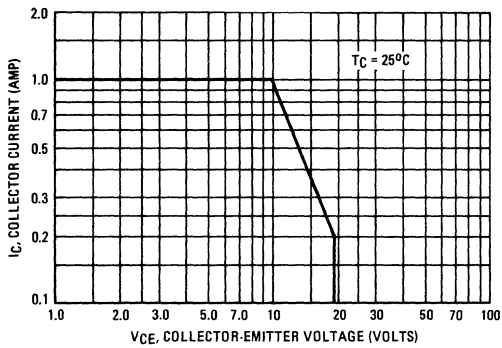


FIGURE 17 – RF POWER DISSIPATION

